Icemos Technology Ltd Product Specification 1003.004101 Issue Date 01 March 2007 11:09:

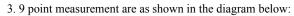
Part Number (7
Part Number (Customer

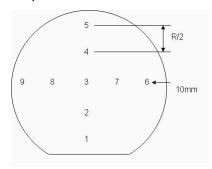
Category	Parameter		Specification	Measurement Method
OverallWafer	1.0	Diameter	100.00 +/- 0.50 mm	
	2.0	Primary Flat Orientation	{110}+/-1 degree	Wafer Vendor
	3.0	Primary Flat Length	32.50 +/- 2.50 mm	Wafer Vendor
	4.0	Secondary Flat Orientation	none	
	5.0	Overall Thickness	624.00 +/- 5.00 μm	ADE, 100%
	6.0	Total Thickness Variation (TTV)	<2.00μm	Guaranteed by Process
	7.0	Bow	<50.00μm	ADE to ASTM F534, 20%
	8.0	Warp	<50.00μm	ADE to ASTM F657, 20%
	9.0	Edge Chips	0	Bright Light, 100% (note 2)
	10.0	Edge Exclusion	5mm	
HandleSilicon	11.0	Handle Growth Method	FZ	Wafer Vendor
	12.0	Handle Orientation	{100} +/- 1 degree	Wafer Vendor
	13.0	Handle Thickness	624.00 +/- 5.00 μm	ADE, 100%
	14.0	Handle Doping Type	N	Wafer Vendor
	15.0	Handle Dopant	Phosphorous	Wafer Vendor
	16.0	Handle Resistivity	1 - 10 Ohmcm	Wafer Vendor
	17.0	Backside Finish	Polished with lasermarking	Wafer Vendor
DeviceSilicon	18.0	LPD Count	<30.00pces	@0.3um, Tencor 6220 particle counter
	19.0	Scratches	0	Bright Light, 100% (note 2)
	20.0	Haze	none	Bright Light, 100% (note 2)

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Part Number		Customer		
Category	Parameter	Specification	Measurement Method	
Shipping Details	Wafer per box :	Max 25		
	Packaging:	Taped Polypropylene Wafer Box Empak, Ultrapak, 100.00mm Antistatic Double Bagging		
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness		
Explanatory Notes	1. Microscope inspec	tion performed using microscope scan as below. 5x objective.		
	2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall			

2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overal Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.





Additional Information